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SEP 18 2006

Docket No. 60173 (71987)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: C. Huang

U.S. SERIAL NO: 10/696,198 EXAMINER: H. Trinh

FILED: October 28, 2003 GROUP: 2814

FOR: MULTI-CHIP PACKAGE DEVICE WITH HEAT SINK AND
FABRICATION METHOD THEREOF

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I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being transmitted by facsimile to the U.S. Patent & Trademark Office by facsimile number 571-273-8300 on September 18, 2006.

By: 
Steven M. Jensen

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir/Madam:

RESPONSE TO OFFICE ACTION

Applicant is in receipt of the Office Action dated May 17, 2006 of the above-referenced application. A request for a one-month extension of time is submitted herewith. Applicant responds to the Office Action as follows.

Claims 1-8 are pending in the application.

Applicant's claimed invention is directed to a multi-chip package device with a heat sink, in which "at least one hollow part extending through the heat sink is formed at an area of the heat sink free of contact with the first chip and the semiconductor package" (see claim 1, emphasis added).